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DATE: May 06, 2021

PCN #: 2478 **REV 3 – FINAL UPDATE**

PCN Title: Additional Wafer Source (GFAB) - Automotive

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



**PRODUCT CHANGE NOTICE**

**PCN-2478 REV 3 – FINAL**

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
August 13, 2020	June 6, 2021	Discrete - Automotive	Additional Wafer Source / Assembly BOM	2478
<b>TITLE</b>				
Additional Wafer Source (GFAB) - Automotive				
<b>DESCRIPTION OF CHANGE</b>				
<p><b>REV 3: This update provides a final listing of affected part numbers for which qualification is complete for the changes listed in the title of the tables below. All applicable qualification reports are attached (embedded in this file).</b></p> <p>This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes is qualifying an additional internal wafer source located in Greenock, Scotland (GFAB), for automotive products.</p> <p>Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure no change to device functionality or electrical specifications in the datasheet. Refer to the attached qualification report embedded in this file (to view, download this PCN file then open it with a PDF viewer to see the attached qual report).</p> <p>In conjunction with adding the wafer source, several additional changes will be implemented on select part numbers to ensure continuity of supply, to standardize manufacturing processes, and to enhance manufacturability. This includes alignment of wafer fab and assembly bill of material (BOM), i.e. wafer process metal system, mold compound, die attach material, lead frame type, bond wire material and/or wire diameter.</p> <p>Please contact your local Diodes Sales representative for samples availability.</p>				
<b>IMPACT</b>				
Continuity of Supply. There will be no change to the Form, Fit or Function of products affected, unless specifically indicated.				
No change in datasheet parameters and product performance.				
<b>PRODUCTS AFFECTED</b>				
Table 1: Additional wafer source (GFAB) Table 2: Additional wafer source (GFAB) and assembly BOM change				
<b>WEB LINKS</b>				
<b>Manufacturer's Notice:</b>	<a href="https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/">https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/</a>			
<b>For More Information Contact:</b>	<a href="https://www.diodes.com/about/contact-us/contact-sales/">https://www.diodes.com/about/contact-us/contact-sales/</a>			
<b>Data Sheet:</b>	<a href="http://www.diodes.com/catalog">http://www.diodes.com/catalog</a>			
<b>DISCLAIMER</b>				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				

**Table 1 - Additional wafer source (GFAB)**

1N5819HWQ-7-F	B180BQ-13-F	B260Q-13-F	B360BQ-13-F	PD3S120LQ-7	PDS360Q-13
B1100BQ-13-F	B180Q-13-F	B270Q-13-F	B360Q-13-F	PD3S130HQ-7	PDS4150Q-13
B1100Q-13-F	B190BQ-13-F	B280Q-13-F	B370Q-13-F	PD3S130LQ-7	PDS4200HQ-13
B120BQ-13-F	B190Q-13-F	B290Q-13-F	B380Q-13-F	PD3S140Q-7	PDS5100HQ-13
B120Q-13-F	B2100Q-13-F	B3100Q-13-F	B390Q-13-F	PD3S160Q-7	PDS5100HQ-13D
B130BQ-13-F	B220AQ-13-F	B320AQ-13-F	B520CQ-13-F	PD3S220LQ-7	PDS5100Q-13D
B130Q-13-F	B220Q-13-F	B320Q-13-F	B530CQ-13-F	PD3S230HQ-7	PDS540Q-13
B140BQ-13-F	B230AQ-13-F	B330AQ-13-F	B540CQ-13-F	PD3S230LQ-7	PDS560Q-13
B140Q-13-F	B240AQ-13-F	B330Q-13-F	B550CQ-13-F	PDS1040Q-13	PDS760Q-13
B150BQ-13-F	B240Q-13-F	B340AQ-13-F	B560CQ-13-F	PDS3100Q-13	SDM160S1FQ-7
B150Q-13-F	B250AQ-13-F	B340BQ-13-F	BAS40WQ-13-F	PDS3100Q-7	SDM20U30Q-7
B160Q-13-F	B250Q-13	B340Q-13-F	BAS40WQ-7-F	PDS3200Q-13	SDM2100S1FQ-7
B170BQ-13-F	B250Q-13-F	B350AQ-13-F	BAT64T5Q-7-F	PDS340Q-13	SDM40E20LAQ-7
B170Q-13-F	B260AQ-13-F	B360AQ-13-F			

**Table 2 – Additional wafer source (GFAB) and assembly BOM change**

B0520LWQ-7-F*	BAS70-04Q-13-F**	BAT46WQ-7-F	BAT54SWQ-7-F*	DFLS140Q-7	SDM20U40Q-7*
B0530WSQ-13-F**	BAS70-04Q-7-F**	BAT54AQ-13*	BAT54TQ-7-F**	DFLS160Q-7	SDM40E20LSQ-7-F
B0530WSQ-7-F**	BAS70-05Q-13-F**	BAT54AQ-7-F*	BAT54TWQ-7-F	DFLS2100Q-7	ZHCS1000QTA
B0540WQ-7-F	BAS70-05Q-7-F**	BAT54AWQ-7-F*	BAT54WQ-13-F*	DFLS230LQ-7	ZHCS350QTA
B140HWQ-7	BAS70-06Q-7-F**	BAT54CQ-13*	BAT54WQ-7-F*	DFLS240LQ-7	ZHCS400QTA**
BAS40-04Q-13-F	BAS70DW-04Q-7-F	BAT54CQ-7-F*	BAT54WSQ-7-F*	DFLS240Q-7	ZHCS400QTC**
BAS40-04Q-7-F	BAS70DW-05Q-7-F*	BAT54CWQ-7-F*	BAT760Q-7**	DFLS260Q-7	ZHCS500QTA
BAS40-05Q-13-F	BAS70Q-7-F	BAT54LPQ-7	DFLS1100Q-7	SD103AWSQ-7-F**	ZHCS506QTA**
BAS40-05Q-7-F	BAS70TWQ-7-F**	BAT54Q-7-F*	DFLS1150Q-7	SD103BWSQ-7-F**	ZLLS1000QTA
BAS40-06Q-13-F*	BAS70W-04Q-7-F	BAT54SDWQ-7-F*	DFLS1200Q-7	SDM03U40Q-7**	ZLLS2000QTA
BAS40-06Q-7-F	BAS70W-05Q-7-F	BAT54SQ-13*	DFLS120LQ-7	SDM1M40LP8Q-7**	ZLLS400QTA
BAS40Q-13-F	BAS70WQ-7-F	BAT54SQ-7-F*	DFLS130LQ-7	SDM20U30LPQ-7*	ZLLS400QTC
BAS40Q-7-F*	BAT1000Q-7-F	BAT54STQ-7-F**	DFLS140LQ-7	SDM20U40Q-13*	ZLLS500QTA

Note 1: "\*" Also affected by Phenitex Wafer Manufacturing Site Change announced via PCN 2462

Note 2: "\*\*" Change bond wire from Cu to Au